

FULLY AUTOMATIC DICING MACHINE

AD3000T

Fast, refined and innovative



TWIN Dicing concept with two opposing Spindles

World's smallest Dicing Machine

Achieved smallest footprint possible utilizing our own core technology.
Size reduced down to 68% by comparison.

World's most efficient Dicing Machine

Delivering fast X-axis (Up to 1,000 mm/sec) and Y-axis (Up to 300 mm/sec) processing speed.
Low Cost of ownership.

Introducing refined Graphic User Interface

Tokyo Seimitsu was the first to Introduce TWIN Dicing Machine equipped with GUI and now refined GUI is available with HELP function as a standard feature for ease of operation.

Ease of maintenance

Widen front access door help improve routine maintenance with ease-of-maintenance in mind.



Tokyo Seimitsu has introduced Japan's first Wafer Dicing Machine, Model A-WD-75A in 1970 and tremendous contribution was made to success of Semiconductor industry with die separation process technology and its long term evolution with precision processing. Vast resource accumulated on Dicing Technology over four decades has enabled us to introduce next generation of Dicing machine, Model AD3000T with latest technology in FLUIDIC ENGINEERING, MECHATRONICS ENGINEERING and ENERGY CONSERVATION to lead the world with Dicing technology.

Main Features

- 1 Optimized spacing by utilizing all components and optional unit well within the compartment**
- 2 Standard Spindles up to 60,000 rpm**
(80,000 rpm as optional)
- 3 Enhanced throughput**
1: X axis 1,000 mm/sec, Y axis 300 mm/sec, and Z axis 80 mm/sec
2: Two Optical Cutter-Set units
3: The Worlds' smallest blade-to-blade distance
- 4 17" LCD touch panel and new GUI**
GUI(Graphical User Interface)
with simple layout and large touch-buttons
allow users' interactive operation
- 5 Easy and simple Kerf check function**
(AI kerf check function)
- 6 Over 10,000 recipes storable**
- 7 USB port as standard**
(USB memory device can be used as external memory)
- 8 Ease-of-maintenance**
Wide maintenance door and front-side accessibility allows easy of routine maintenance
- 9 Optimized vacuum controller**
Reduces 50 % of air consumption compared with existing model



New GUI ►

Specifications

Max. work size		Φ 305 mm
Max. number of frames		12 inch (430 Φ)
Spindle	Rotation	60,000 min-1 OP:80,000 min-1
	Max. blade diameter	Φ 60 mm (2-Inch)
	Rated Output	1.8 KW
X axis	Available cutting range	310 mm
	Max. Speed	1000 mm/s
Y1/Y2 axes	Available cutting range	310 mm
	Max. Speed	300 mm/s
	Resolution	0.078 μm
	Accuracy	0.002 mm / 310 mm
Z1/Z2 axes	Stroke	34 mm
	Resolution	0.002 μm
	Max. Speed	80 mm/sec
	Repeatability	0.001 mm
θ axis	Range of rotation	380°
Misc	Voltage	3 Phase AC200 to 220 V ±10 % (Transformer adoptable)
	Power consumption	6.0 kVA (MAX)
	Air pressure	0.55 to 0.7 MPa
	Avg. Air consumption	210 L/min (0.55 MPa)
	Avg. Clean Air consumption	140 L/min
	Cutting Water, and others (pressure)	0.3 to 0.5 MPa
	Cutting Water, and others (Max Flow)	Cutting Water:10.0 L/min Water curtain:3.0 L/min Others: 0.6 L/min
	Cooling Water (pressure)	0.3 to 0.5 MPa
	Cooling Water (Max Flow)	3.4 L/min (0.3 MPa)
Size (W*D*H)	Exhaust	5.0 m ³ / min more
	Weight	1290 mm x 1530 mm x 1900 mm
Weight		1300 kg

Maintenance



Set up space

Tokyo Seimitsu has succeeded
with footprint reduction
by comparison with existing model

